2-1445051-5 ACTIVE

MATE-N-LOK | Micro MATE-N-LOK

TE Internal #: 2-1445051-5

Rectangular Power Connectors, Header, Plug, Wire-to-Board, 5 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0,

Micro MATE-N-LOK

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Connectors > Power Connectors > Rectangular Power > Rectangular Power Connectors











Rectangular Power Connector Type: Header

Connector & Housing Type: Plug
Connector System: Wire-to-Board

Number of Positions: 5

Centerline (Pitch): 3 mm [.118 in]

Features

Product Type Features

Header Type	Fully Shrouded
Rectangular Power Connector Type	Header
Connector & Housing Type	Plug
Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	5
PCB Mount Orientation	Vertical
Number of Power Positions	5
Number of Rows	1

250 VDC

Operating Voltage



Multiple Contact Types PCR Contact Termination Area Plating Material Thickness PCR Contact Layout Contact Layout Inline Contact Mating Area Plating Material Contact Current Rating (Max) Contact Retention Within Housing Without Contact Type PCR Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Thickness Termination Features Termination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Strain Relief Without Mating Alignment Type Polarization Mating Alignment With Panel Mount Feature Without PCR Mount Retention Type Mating Retention Type Conrector Mounting Type Board Mount Housing Retention Type Conrector Mounting Type Board Mount Housing Features PCR Mount Retention Material Phosphor Bronze Contectine (Pitch) Housing Color Housing Material Dimensions Contectine (Pitch) Housing Material Dimensions		
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Housing Features PCB Mount Retention Material Phosphor Bronze Centerline (Pitch) 3 mm[.118 in] Housing Color Black Housing Material High Temperature Nylon Dimensions	Mating Retention Type	Locking Tab
PCB Mount Retention Material Centerline (Pitch) Housing Color Housing Material Black High Temperature Nylon Dimensions	Connector Mounting Type	Board Mount
Centerline (Pitch) Housing Color Housing Material High Temperature Nylon Dimensions	Housing Features	
Housing Color Housing Material High Temperature Nylon Dimensions	PCB Mount Retention Material	Phosphor Bronze
Housing Material High Temperature Nylon Dimensions	Centerline (Pitch)	3 mm[.118 in]
Dimensions	Housing Color	Black
	Housing Material	High Temperature Nylon
Compatible Inquistion Diameter (May)	Dimensions	
Compatible insulation Diameter (wax) .o mm[.o in]	Compatible Insulation Diameter (Max)	.6 mm[.6 in]
PCB Thickness (Recommended) .06 mm[1.57 in]	PCB Thickness (Recommended)	.06 mm[1.57 in]
Wire Size .051 – .517 mm ²	Wire Size	.051 – .517 mm²
Usage Conditions	Usage Conditions	



Operating Temperature Range	-40 - 105 °C[-40 - 221 °F]
Operation/Application	
Circuit Application	Power
Industry Standards	
CSA Rating	Certified, LR 7189
Glow Wire Material Rating	Material with GWFI 850°C, Material with GWIT ≥ 775°C
UL Rating	Recognized
Agency/Standard	CNR, USR
Approved Standards	UL E28476
UL Flammability Rating	UL 94V-0
Glow Wire Rating	GWT 750°C (Without Flame)
Packaging Features	
Packaging Quantity	182
Packaging Method	Box & Tray, Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous

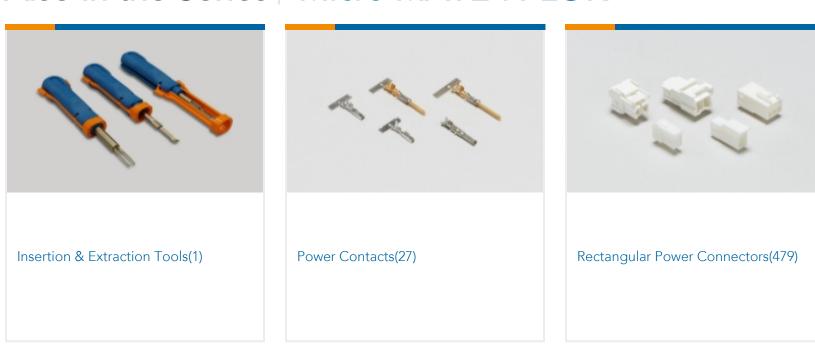


materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

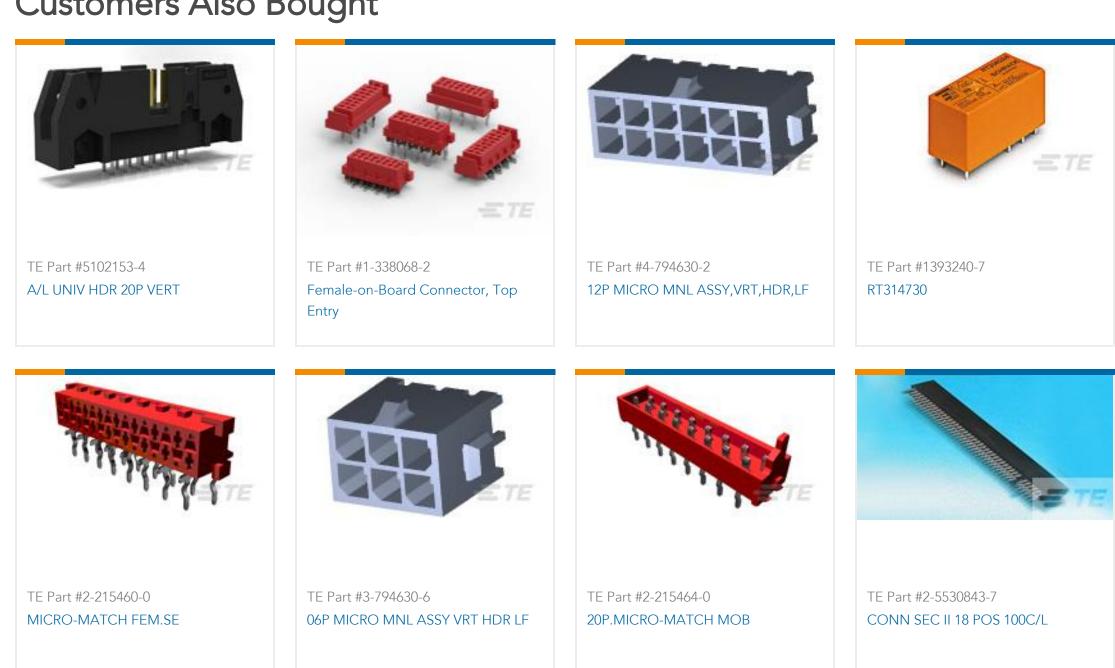
Compatible Parts



Also in the Series | Micro MATE-N-LOK



Customers Also Bought



Documents



Product Drawings

MICRO MNL HDR ASSY S/ROW LF

English

CAD Files

Customer View Model

ENG_CVM_CVM_2-1445051-5_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-1445051-5_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-1445051-5_B.3d_stp.zip

English

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Datasheets & Catalog Pages

SOFT_SHELL_PIN_AND_SOCKET_CONNECTORS_CATALOG

English

MICRO MATE-N-LOK CONNECTOR SYSTEM

English

Product Specifications

Application Specification

English